


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M93C56-RDW6TP	PT6P*0C561KA	A	3068	20-07-2021
	Amount	UoM	Unit type	ST ECOPACK Grade
	34.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
TSSOP	NAC	8	L Bend	
Comment	Package : 6P TSSOP 8 BODY 4.4 PITCH 0.65 0079397			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-19th January 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	PT6P*QC561KA				7000000.0	999999.8
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.508	mg	supplier	die	Silicon (Si)	7440-21-3		0.489	mg	962598	14382
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	3937	59
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	1969	29
Lead-frame	M-011 Other inorganic materials	14.518	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	31496	471
				supplier	alloy	Copper(Cu)	7440-50-8		13.966	mg	962002	410768
				supplier	alloy	Nickel(Ni)	7440-02-0		0.436	mg	29998	12809
Lead-frame Coating	M-011 Other inorganic materials	0.062	mg	supplier	alloy	Silicium (Si)	7440-21-3		0.094	mg	6500	2775
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.022	mg	1500	640
				supplier	coating	Nickel (Ni)	7440-02-0		0.058	mg	942580	1708
Die Attach	M-011 Other inorganic materials	0.049	mg	supplier	coating	Palladium (Pd)	7440-05-3		0.002	mg	29665	54
				supplier	coating	Gold (Au)	7440-57-5		0.002	mg	27755	50
				supplier	glue or soft solder	Silver(Ag)	7440-22-4		0.037	mg	760000	1095
Wires	M-011 Other inorganic materials	0.019	mg	supplier	glue or soft solder	Oxiranylmethoxy-phenyl-methylene-bisoxiran	13561-08-5		0.006	mg	120000	173
				supplier	glue or soft solder	Phenol resin	9003-35-4		0.001	mg	30000	43
				supplier	glue or soft solder	Epoxypropoxy butane polymer	2425-79-8		0.001	mg	30000	43
				supplier	glue or soft solder	Diglycidyl phenyl allyl ether	EC 417-470-1		0.002	mg	50000	72
Encapsulation	M-011 Other inorganic materials	18.844	mg	supplier	glue or soft solder	Polyoxypropylenediamine	9046-10-6		0.000	mg	10000	14
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.019	mg	1000000	546
				supplier	Moulding Compound	Epoxy Resin	85954-11-6		1.434	mg	76108	42183
Finishing	M-011 Other inorganic materials	0.001	mg	supplier	Moulding Compound	Phenol Resin	26834-02-6		0.956	mg	50739	28122
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		16.282	mg	864020	478882
				supplier	Moulding Compound	Carbon black	1333-86-4		0.096	mg	5074	2812
connections coating	M-011 Other inorganic materials	0.001	mg	supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.076	mg	4059	2250
				supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	940951	17
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	30507	1
connections coating				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	28542	1

